



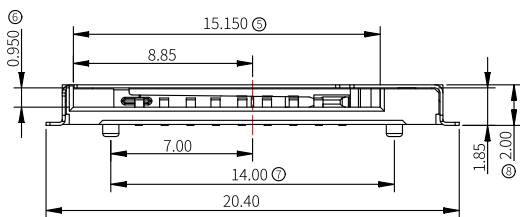
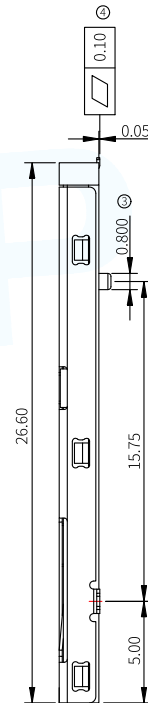
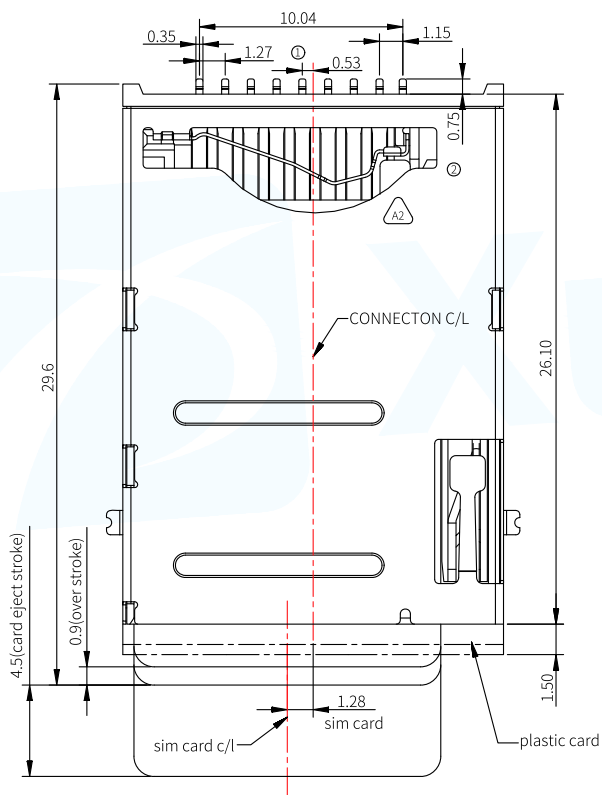
SIM-012-ACP9
W26.10xD19.20xH1.85

| | |
|--|---|
| PIN 数(Number of contacts) : 9PIN | 耐电压(Withstand voltage) : 500V AC for 1 min |
| 操作方式(Operation mode): 自弹式/PUSH/PUSH | 操作寿命(Operation life): 5,000 Cycles Min |
| 温度范围(Operating temp): -40°C TO +80°C | 焊接温度(Welding temperature): 260±5° 5s |
| 额定负荷(Rated load): 0.5A PER PIN. | 焊接方式(Welding mode): 贴片式/SMT |
| 接触电阻(Contact resistance): 100mΩ max. | 包装方式(Packaging method): 卷带/Tape & Reel (TR) |
| 绝缘电阻(Insulation resistance): 1000MΩ min. | 最小包装(Minimum packing): 500/PCS |

外形尺寸 (UNIT:MM) / Size Chart

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更多资料请参考技术选型档!



Specification

Electrical Characteristics:

- Current Rating: 0.5A
- Withstanding Voltage: AC500V r.m.s
- Insulation Resistance: 1000Megohms Minimum at DC 500V.
- Contact Resistance: 100Miliohms Maximum.

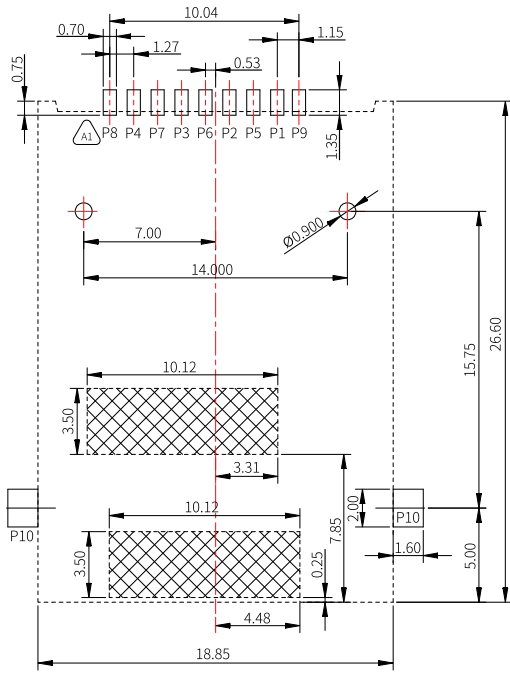
Mechanical Characteristics:

- Mating Cycles: 10,000 Insertions.
- Environmental: Operating Temperature: -40°C to +85°C

Material:

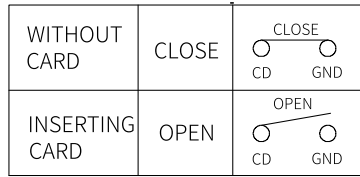
- 1.Housing: HI-TEMP PLASTIC UL 94V-0 Rated.
- 2.Contact: Copper Alloy
- 3.Shell: Copper Alloy

Can accord with management standards for "environment-related substances to be controlled"

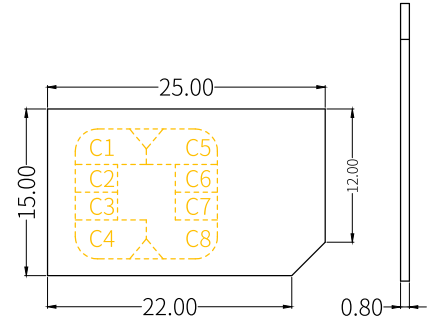


PCB焊盘区(PAD AREA)
 禁区(KEEP OUT AREA)
RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ± 0.05

Circuit Diagram for Detect Switch



● MINI SIM



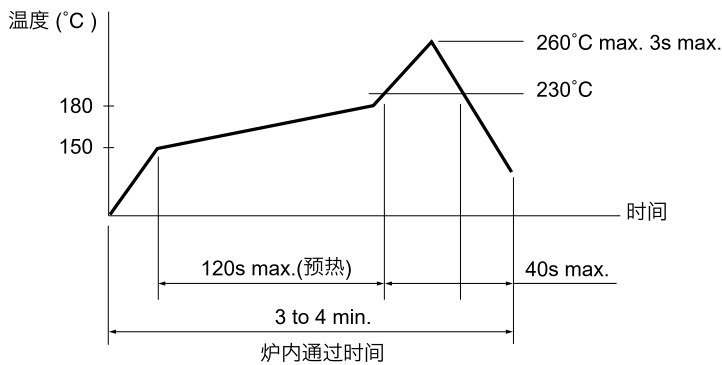
● 引脚定义/Pin Definition

| SIM PIN ASSIGNMENT | | | |
|--------------------|-------|------|--------------------|
| PIN# | NAME | TYPE | DESCRIPTION |
| C1 | 供电电压 | 1 | VCC |
| C2 | 重置 | 1 | RST |
| C3 | 时钟 | 1 | CLK |
| C4 | 保留项 | | Reserved |
| C5 | 接地 | 1 | GND |
| C6 | 程序电压 | 1 | VPP |
| C7 | 输入输出 | 1 | I/O |
| C8 | 保留项 | | Reserved |
| C9 | 卡检测开关 | 1 | Card detect switch |
| C10 | 接地 | 1 | GND |

焊接条件 / Welding conditions

● 回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products
 温度分布/Temperature distribution



● 手焊式/Hand welding

| 项目/Project | 条件/condition |
|-----------------------------------|--------------|
| 焊接温度 Welding temperature | 350°C max. |
| 持续焊接时间 Continuous welding time | 3s max. |
| 焊剂斗容量 Flux bucket capacity | 60W max. |

● 浸焊式/Immersion soldering

| 项目/Project | 条件/condition |
|------------------------------------|---|
| 助焊剂附着量 Flux adhesion | 不附着于零部件贴装面的程度 Not attached to the mounting surface of components |
| 预热温度 Preheating temperature | 印刷电路板焊接面的周围温度 100°C max. The temperature around the welding surface of PCB is 100 °C max |
| 预热温度时间 Preheat temperature time | 60s max. |
| 焊接温度 welding temperature | 260°C max. |
| 焊接浸渍时间 Welding immersion time | 5s max. |
| 焊接次数 Welding times | 2 times max. |

注:

1. 加热方式:以远红外线上下加热方式。
2. 温度测量:用 $\Phi 0.1\sim 0.2$ 的 CA(K)或 CC(T)测量位置在焊接连接部(锡/铜箔面)。
3. 固定方式:采用耐热胶带。